

# 产品规格书

# SPECIFICATION

CUSTOMER 客户： \_\_\_\_\_

PRODUCT 产品： \_\_\_\_\_ SAW FILTER \_\_\_\_\_

MODEL NO 型号： \_\_\_\_\_ HDBF07015A64 SF6-4 \_\_\_\_\_

PREPARED 编制： 沟康君 CHECKED 审核： \_\_\_\_\_

APPROVED 批准： \_\_\_\_\_ D A T E 日期： \_\_\_\_\_ 2010-11-11 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

### 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

## 1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07015A64 used for the page system.

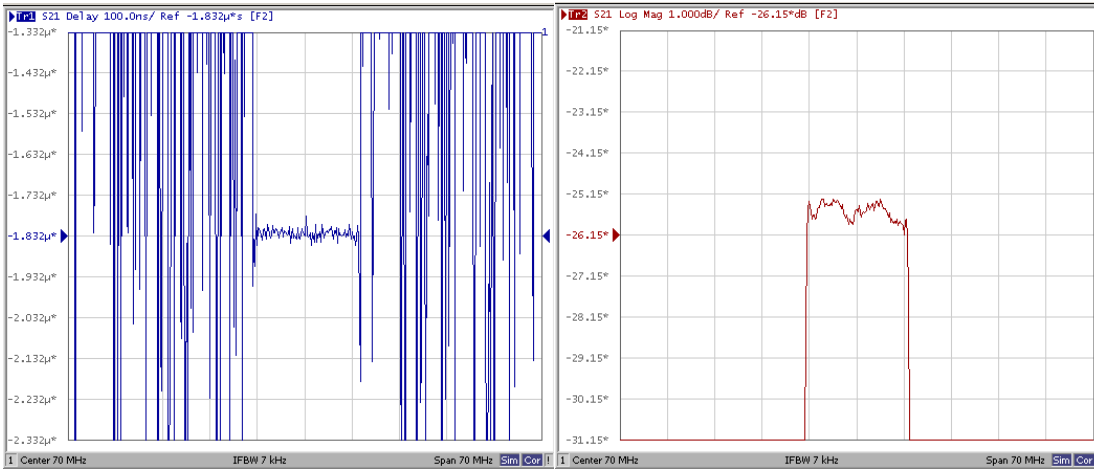
## 2. ELECTRICAL SPECIFICATION

Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45°C to +85°C
Operation Temperature Range	-40°C to +85°C

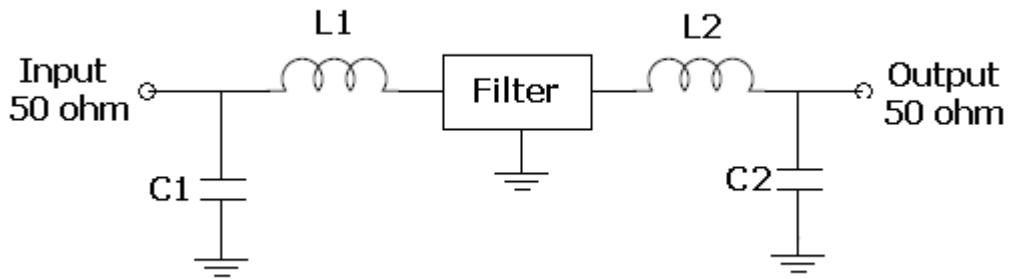
### Electronic Characteristics

Parameter	Min.	Typical.	Max.	Unit
Center Frequency	69.8	70	70.2	MHz
Insertion loss		25	26	dB
Passband ripple(-1 dB)		0.9	1.5	dB
-1dB Bandwidth	14.2	14.8		MHz
-3dB Bandwidth	15	15.2		MHz
-40dB Bandwidth		16.3	16.4	MHz
Rejection: 16MHz—63MHz	50	55		dB
77MHz—140MHz	55	60		
Absolute Delay		3.9	4.2	usec
Group Delay Variation		100	120	nsec
Temperature Coefficient		-87		ppm/°C
Package Size	SF6-4			

**Typical Frequency Response**



**3. TEST CIRCUIT**

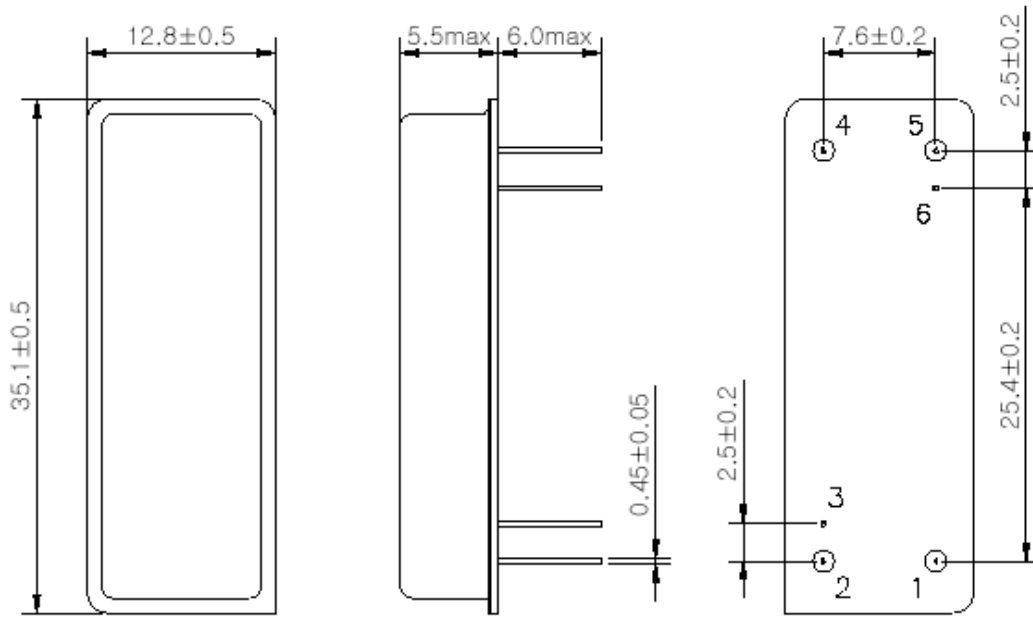


Input : L1 = 120 nH , C1 = 0 pF

Output : L2 = 120 nH , C2 = 9 pF

\* Component values may change depending on board layout.

**4.DIMENSION**



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 High temperature exposure

Subject the device to  $+85^{\circ}\text{C}$  for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-2 Low temperature exposure

Subject the device to  $-40^{\circ}\text{C}$  for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-3 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

### 5-5 Solderability

Subject the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

**5-6 Mechanical shock**

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

**5-7 Vibration**

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

**6. REMARK****6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

**6.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

**6.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.